



Material Content Data Sheet



Sales Product Name		IDV08E65D2		Issued		20. July 2018		
MA#		MA001403376						
Package		PG-TO220-2-23		Weight*		2152.33 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.448	0.02	0.02	208	208
leadframe	non noble metal	iron	7439-89-6	1.021	0.05		475	
	inorganic material	phosphorus	7723-14-0	0.306	0.01		142	
	non noble metal	copper	7440-50-8	1020.042	47.39	47.45	473925	474542
wire	non noble metal	aluminium	7429-90-5	1.658	0.08	0.08	770	770
encapsulation	organic material	carbon black	1333-86-4	2.244	0.10		1043	
	plastics	epoxy resin	-	210.949	9.80		98010	
	inorganic material	silicondioxide	60676-86-0	908.878	42.23	52.13	422277	521330
leadfinish	non noble metal	tin	7440-31-5	5.534	0.26	0.26	2571	2571
plating	non noble metal	nickel	7440-02-0	0.797	0.04	0.04	370	370
solder	non noble metal	antimony	7440-36-0	0.045	0.00		21	
	noble metal	silver	7440-22-4	0.112	0.01		52	
	non noble metal	tin	7440-31-5	0.292	0.01	0.02	136	209
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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